permacol® bv
industrial adhesives

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PERMACOL 2035Z-SERIES

DESCRIPTION:

The PERMACOL 2035Z-series are smooth, thixotropic, one component adhesives on epoxy base for SMT purposes. Adhesives of the PERMACOL 2035Z-series can be applied, dispensed or screen printed, without stringing and will not sag whilst curing. These thixotropic adhesives hold electronic components in position and prevent movement due to vibration even before curing.

The cured adhesive has excellent electric properties and heat resistance during soldering.

In the PERMACOL 2035Z-series, we supply adhesives in different viscosities, adjusted to the method applied or type of electronic component to bond. This viscosity assigned by the extensions /15, /25, /30 and /40 are:

PERMACOL VISCOSITY TYPE	MAIN APPLICATION
2035Z/15R (red)	Dispensable adhesive for larger components, High dispensing temperatures possible (3040□C), Stencil printing.
2035Z/25R (red) or 2035Z/25G (yellow)	SMD-adhesive for stencil printing. High viscosity.
2035Z/30R (red) or 2035Z/30G (yellow)	SMD-adhesive for stencil printing / dispensing with high viscosity.
2035Z/40G (yellow)	SMD-adhesive for stencil printing / dispensing.

	2035Z/15	2035Z/25	2035Z/30	2035Z/40
Wet strength	1.200 Pa	1.500 Pa	1.000 Pa	1.900 Pa
Viscosity at D=30/s 23°C	65 Pa.sec	80 Pa.sec	130 Pa.sec	90 Pa.sec

It must be clear that the curing time depends on several parameters. Oven capacity, board design, type of components on Printed Circuit Board, and type of Printed Circuit Board (multilayers have higher heat capacity) can influence the cure speed.

SURFACE TEMPERATURE	MINIMUM HEATING TIME
100°C	6 minutes
125°C	2 minutes
150°C	90 seconds

Storage stability:
PERMACOL SMD adhesives can be stored in its original packaging from 5°C to 7°C for 6 month. Refrigerated adhesives must be allowed to return to room temperature before use. For screen printing adhesives, contamination of the unused material will be avoided if no material is returned to its original packaging.

CLEANING:

At room temperature, the remaining uncured adhesive can be removed and cleaned by means of solvents as Ethanol, Acetone, Isopropylalcohol (IPA), or gamma-Butyrolactone (PC66).

Cured adhesives must be removed mechanically. To avoid damage of components and/or PCB, it is advised to heat up the adhesive or bond over 100°C (over the softening point of the adhesive). At this temperature, the adhesive dot will be soft and the component can easily be removed by means of torsion.

PACKAGING:

The PERMACOL 2035Z-series can be supplied bubble free in all dispenser-specific syringes, tins, pots, and Eurosyringes.

HANDLING AND SAFETY PRECAUTIONS:

The PERMACOL 2035Z-series is for industrial purposes only. Read Material Safety Data Sheets (MSDS) prior to using product. Avoid contact with eyes, skin or clothing because this material may cause eye irritation, skin irritation or allergic skin reaction if prolonged or repeated expose is present, and is harmful if inhaled or swallowed. Wear eye protection and impervious gloves when handling, keep container closed when not in use.